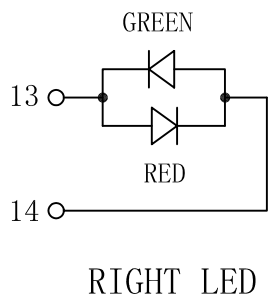
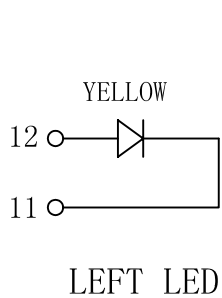
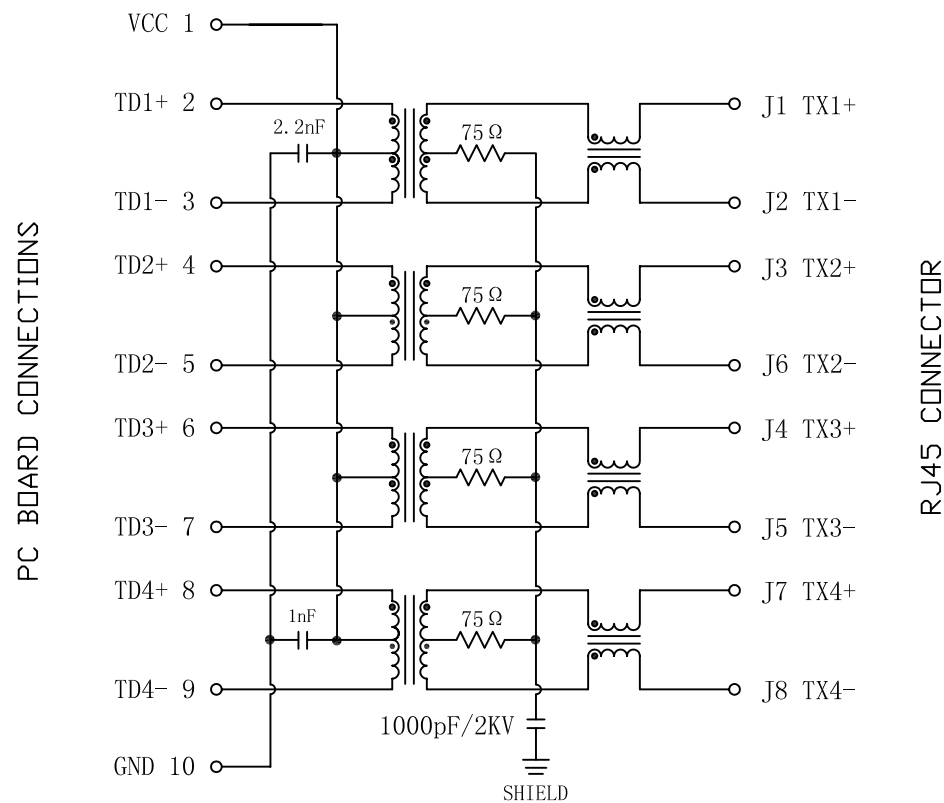


Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2011/12/02	

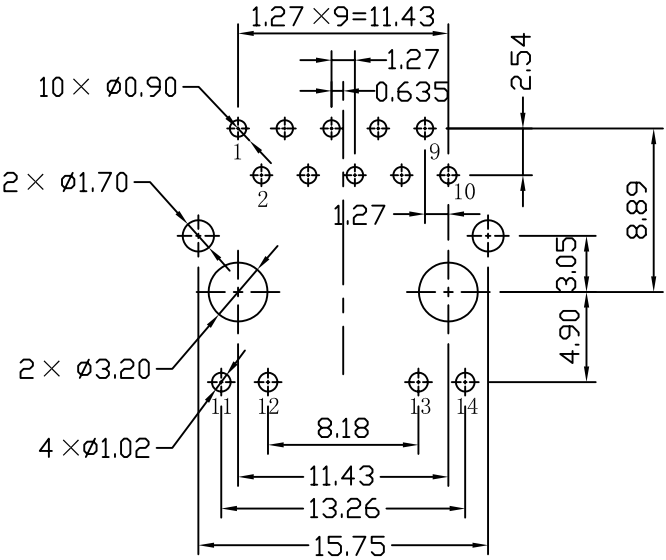
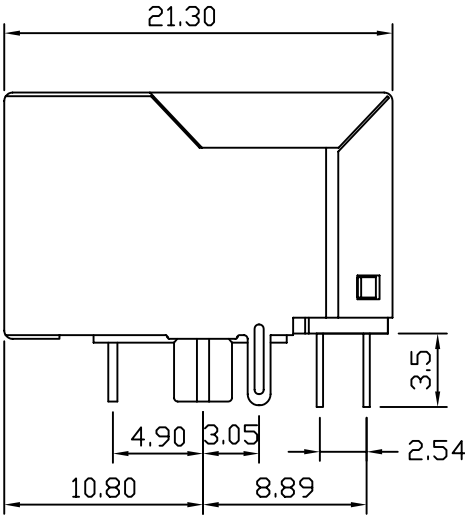
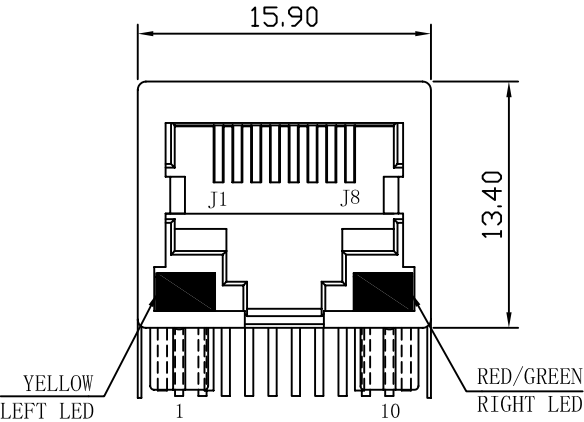


ELECTRICAL SPECIFICATIONS @25°C

- Turn Ratio($\pm 2\%$):
TX=1CT : 1CT RX=1CT : 1CT
- Inductance OCL: 350uH MIN
@100KHz, 0.1V, 8mA DC Bias
- Insertion Loss:
-1.0dB MAX @ 1~100MHz
- Return Loss(@100 Ω ± 15 Ω):
-16dB MIN @1~10MHz
-14dB MIN @40MHz
-12dB MIN @60MHz
-10dB MIN @80~100MHz
- Cross talk:
-47dB MIN @20MHz
-40dB MIN @40MHz
-37dB MIN @60MHz
-35dB MIN @80MHz
-33dB MIN @100MHz
- Differential to Common Mode Rejection:
-33dB MIN @1~100MHz
- CMRR:
-30dB MIN @1~100MHz
- Hipot Test: 1500Vrms MIN
- Operating Temperature Range: -40°C TO +85°C.

X:X ± 0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED		
X:XX ± 0.20	CHKD:	TITLE: RJ45 Connector with 1000 Base-T Integrated Magnetics		
X:XXX ± 0.05	DR: TOM			
ANGLES $\pm 1^\circ$	UNIT: mm	PART NO. : LPJG4896F91NL		
	SCALE: 2/1	SHEET: 1/2	REV: A	DWG NO. : LP11120201

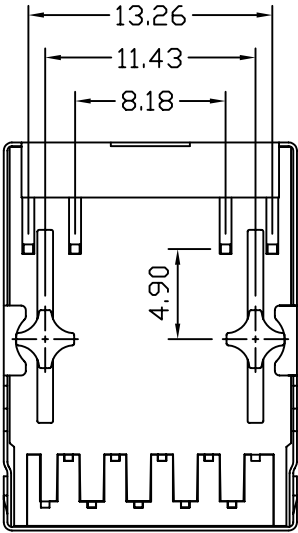
REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2011/12/02	



SUGGESTED PCB LAYOUT(TOP VIEW)

NOTES:

- 1.Designed to support application,such as SOHO(ADSL modems),LAN-on-Motherboard(LOM),hub and Switches.
- 2.Meets IEEE 802.3 specification
- 3.Connector Materials:
Housing:Thermoplastic UL94V-0
Contact/Shield: Copper alloy
Shield plating: Nickel
Contact plating: Gold 6 micro-inches min. In contact area.
- 4.Wave solder tip temperature: 265℃ Max
Wave solder tip temperature time: 5 Sec Max



X:X ±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED		
X:XX ±0.20	CHKD:	TITLE: RJ45 Connector with 1000 Base-T Integrated Magnetics		
X:XXX ±0.05	DR: TOM			
ANGLES ±1°	UNIT: mm	PART NO. : LPJG4896F91NL		
	SCALE: 2/1	SHEET: 2/2	REV: A	DWG NO. : LP11120201